



Customized Ag Paste Product Lines

Parameter	Test/ Measure	DX-30	DX-09E	DX-09G-4	DX-23
Viscosity (cP) @25deg.C	E-viscometer @5rpm	8,500 ± 1,000	20,000 ± 5,000	20,000 ± 5,000	45,000±5,000
Thixotropic index @25deg.C	0.5rpm/5rpm	4.0	--	--	1.1
Volume resistance	Ohm.cm	1*10 ⁻⁴	5*10 ⁻⁵	8*10 ⁻⁵	~10 ⁻⁴
Curing condition		130 °C for 60min	80 °C for 30min	80 °C for 30min	180 °C for 20sec
Recommended process		Dispensing	Dispensing	Dispensing	Dispensing
Application		Electronics Joint	Electronics Joint	Electronics Joint	Electronics Joint
Remark				Low Temp. Curing Good adhesion on metal finishes	Snap Curing